

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please amend claim 48 as follows:

Listing of Claims:

1-47. (Cancelled)

48. (Currently Amended) A method for planarizing a microelectronic substrate, comprising:

biasing a first annular part of the microelectronic substrate against a planarizing medium with a first force by engaging the first annular part with a first portion of a flexible membrane having a first thickness;

biasing a second annular part of the microelectronic substrate against the planarizing medium with a second force greater than the first force by engaging the second annular part with a second portion of the flexible membrane having a second thickness greater than the first thickness, the second annular part located in a peripheral region of the microelectronic substrate and the first annular part located in a region of the microelectronic substrate outside the peripheral region, the substrate being held stationary relative to the membrane as the first annular part and the second annular part of the substrate is biased against the planarizing medium; and

moving at least one of the microelectronic substrate and the planarizing medium relative to the other to remove material from the microelectronic substrate.

49. (Cancelled)

50. (Original) The method of claim 48 wherein the membrane has a first surface facing toward the microelectronic substrate and a second surface facing generally opposite the first surface, further wherein biasing the microelectronic substrate against the

planarizing medium includes biasing a generally flat support member against the second surface of the membrane.

51. (Original) The method of claim 48 wherein biasing the microelectronic substrate against a planarizing medium includes biasing the microelectronic substrate against a first portion of a polishing pad, further wherein moving the at least one of the microelectronic substrate and the planarizing medium includes advancing the polishing pad from a supply roller to a take-up roller to engage a second portion of the polishing pad with the first and second parts of the microelectronic substrate.

52. (Original) The method of claim 48 wherein moving at least one of the microelectronic substrate and the planarizing medium relative to the other includes moving the first part of the microelectronic substrate and the planarizing medium at a first linear velocity relative to each other and moving the second part of the microelectronic substrate and the planarizing medium at a second linear velocity relative to each other, further wherein removing material from the microelectronic substrate includes removing material from the first part of the microelectronic substrate at a first rate and removing material from the second part of the microelectronic substrate at a second rate approximately the same as the first rate.

53. (Original) The method of claim 48 wherein the membrane is the first of a first and second membrane, each membrane having a first portion with a first thickness and a second portion with a second thickness, a ratio of the first thickness to the second thickness of the first membrane having a first value, a ratio of the first thickness to the second thickness of the second membrane having a second value different than the first value, further comprising selecting the first membrane from the first and second membranes.

54-59. (Cancelled)

60-127. (Not entered)